

## PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM3139	TQFN-3×3-16L	-40°C to +85°C	SGM3139YTQ16G/TR	3139TQ XXXXX	Tape and Reel, 3000
	TDFN-3×3-10L	-40°C to +85°C	SGM3139YD10G/TR	SGM 3139D XXXXX	Tape and Reel, 3000

NOTE: XXXXX = Date Code and Vendor Code.

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

## ABSOLUTE MAXIMUM RATINGS

$V_{IN}$  to GND..... -0.3V to 6V  
 The Other Pins to GND..... -0.3V to 6V  
 Power Dissipation,  $P_D$  @  $T_A = 25^\circ\text{C}$   
 TQFN-3×3-16L..... 1.47W  
 TDFN-3×3-10L..... 1.67W  
 Storage Temperature Range..... -40°C to +150°C  
 Junction Temperature..... +150°C  
 Operating Temperature Range..... -40°C to +85°C  
 Lead Temperature (Soldering 10 sec)..... +260°C  
 ESD Susceptibility  
 HBM..... 4000V  
 MM..... 400V

## OVERSTRESS CAUTION

Stresses beyond those listed may cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational section of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

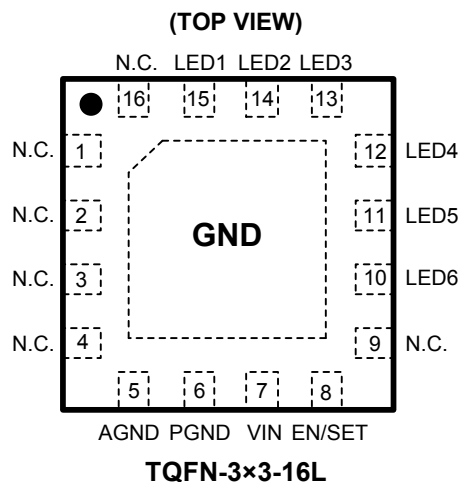
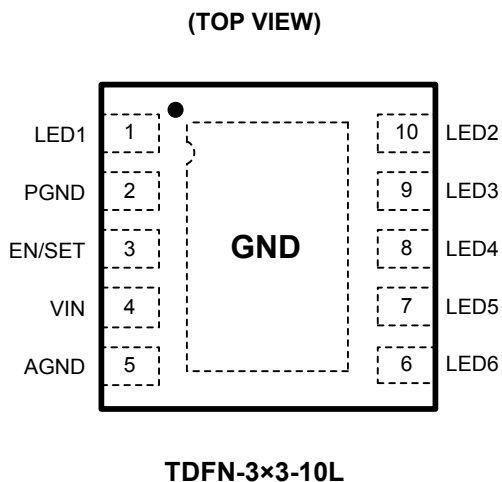
## ESD SENSITIVITY CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time.

## PIN CONFIGURATIONS



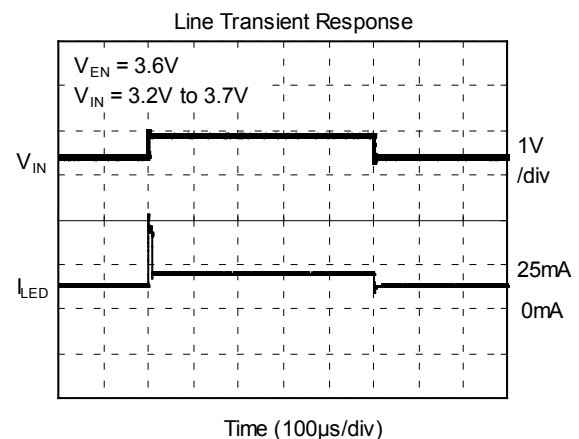
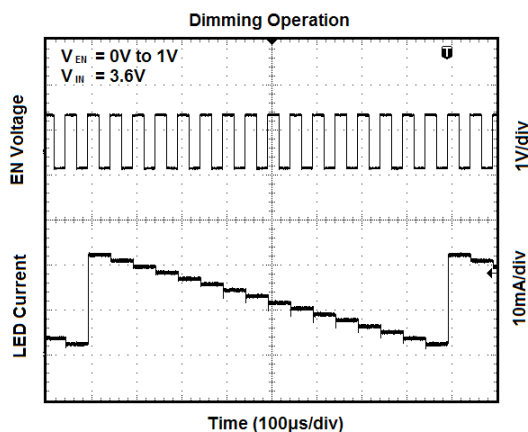
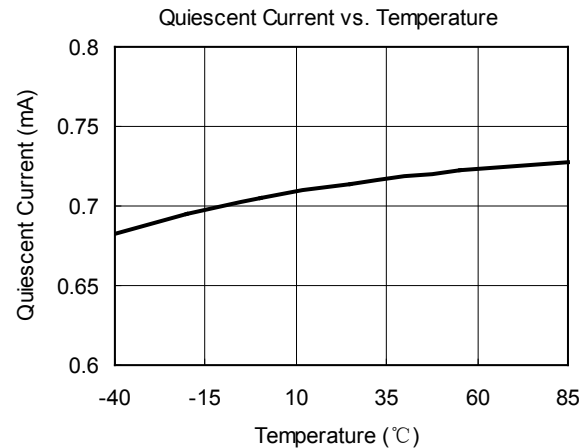
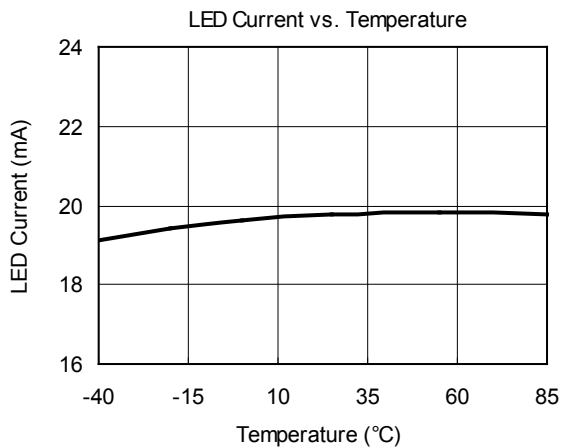
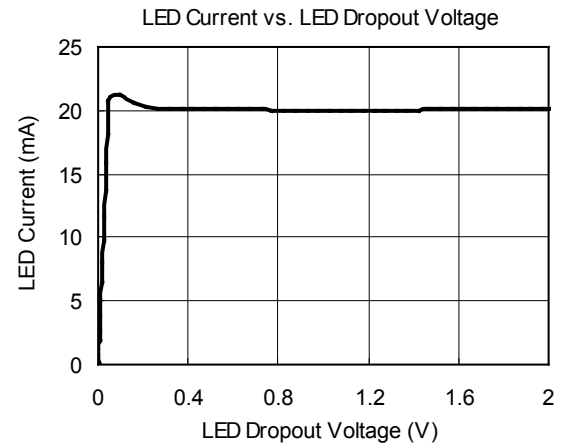
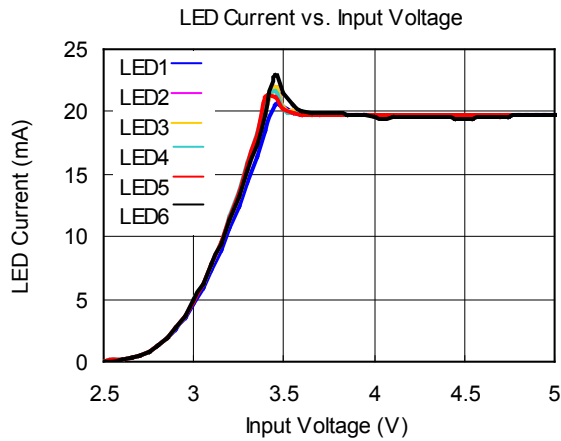
## PIN DESCRIPTION

PIN NUMBER		PIN NAME	PIN FUNCTION
TQFN-3×3-16L	TDFN-3×3-10L		
5	5	AGND	Analog Ground.
6	2	PGND	Power Ground.
7	4	VIN	Power Input Voltage.
8	3	EN/SET	Enable Input (Active High). 1-wire interface for LED Dimming connects to GPIO pin of MCU.
1, 2, 3, 4, 16	—	N.C.	No Internal Connection.
10	6	LED6	Current Sink for LED6. Connected to cathode of external white LED.
11	7	LED5	Current Sink for LED5. Connected to cathode of external white LED.
12	8	LED4	Current Sink for LED4. Connected to cathode of external white LED.
13	9	LED3	Current Sink for LED3. Connected to cathode of external white LED.
14	10	LED2	Current Sink for LED2. Connected to cathode of external white LED.
15	1	LED1	Current Sink for LED1. Connected to cathode of external white LED.
GND	GND	Exposed Pad	Exposed pad should be soldered to PCB board and connected to GND.

**ELECTRICAL CHARACTERISTICS**(V<sub>IN</sub> = 3.6V, C<sub>IN</sub> = 1μF, T<sub>A</sub> = +25°C, unless otherwise noted.)

PARAMETER		SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Operation Voltage Range		V <sub>IN</sub>		2.5		5.0	V
EN/SET Pull Low Current			V <sub>EN/SET</sub> = 1.8V		0.01		μA
Quiescent Power Supply Current		I <sub>Q</sub>	V <sub>IN</sub> = 5.0V, LED OFF		0.72		mA
Shutdown Current		I <sub>SHDN</sub>	V <sub>EN/SET</sub> = 0V, V <sub>IN</sub> = 5.0V		0.1	5	μA
I <sub>LEDx</sub> Accuracy		I <sub>LED-ERR</sub>		-10		+10	%
LED Current Deviation Matching		D <sub>LED</sub>		-3		+3	%
LED Dropout Voltage		V <sub>LED</sub>	I <sub>LEDx</sub> = 20mA, V <sub>LED</sub> @ I <sub>LEDx</sub> = 90% × I <sub>LED</sub>		35		mV
EN/SET Low Time for Shutdown		T <sub>SHDN</sub>			1.6		ms
EN/SET Low Time for Dimming		T <sub>LO</sub>		0.5		500	μs
EN/SET High Time for Dimming		T <sub>HI</sub>		0.5			μs
EN/SET Threshold	Logic-High Voltage	V <sub>IH</sub>	V <sub>EN</sub> > V <sub>IH</sub> for Enable IH	1.2			V
	Logic-Low Voltage	V <sub>IL</sub>	V <sub>EN</sub> < V <sub>IL</sub> for Disable IL			0.5	V
Thermal Shutdown Temperature					145		°C
Hysteresis Temperature					10		°C

## TYPICAL PERFORMANCE CHARACTERISTICS



The block diagram illustrates the internal architecture of the LED driver. It features three main functional blocks: a '16 Steps Pulse Dimming Controller', a 'Shutdown Delay' block, and a 'Low Dropout Current Source'. The input voltage  $V_{IN}$  is connected to the top of the 'Low Dropout Current Source' block. The 'EN/SET' input pin is connected to a node that branches to the '16 Steps Pulse Dimming Controller' and the 'Shutdown Delay' block. The outputs of both the '16 Steps Pulse Dimming Controller' and the 'Shutdown Delay' block are connected to the input of the 'Low Dropout Current Source'. The 'Low Dropout Current Source' block provides six output channels, labeled LED1 through LED6, which are connected to the respective LEDs.

## APPLICATION INFORMATION

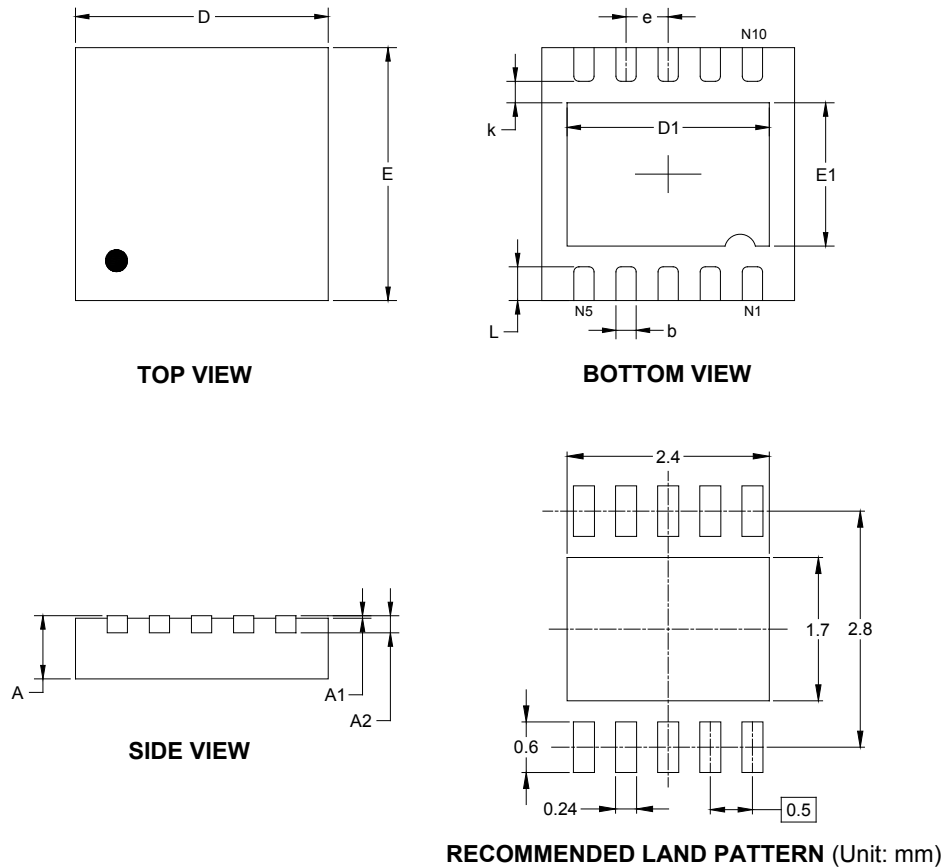
The SGM3139 supports up to 6 white LEDs. The 6 LEDs are connected from VIN to TQFN-3×3-16L package's pin 10, 11, 12, 13, 14 and 15 respectively. For TDFN-3×3-10L package, cathodes of white LEDs are connected to pin1, 6, 7, 8, 9, and 10. The LED pins can be left floating if the white LEDs are not used.

The SGM3139 implements a pulse dimming method to control the brightness of white LEDs. Users can easily configure the LED current from 1.25mA to 20mA by a serial pulse. The dimming of white LEDs' current can be achieved by applying a pulse signal to the EN/SET pin. There are totally 16 steps of current that could be set by users. The detail operation of brightness dimming is showed in the Figure 3.



## PACKAGE OUTLINE DIMENSIONS

### TDFN-3×3-10L

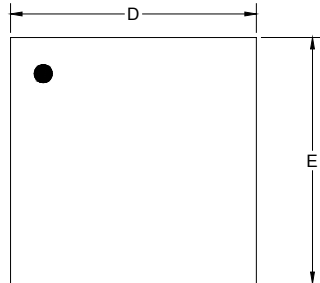


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203 REF		0.008 REF	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.103
E	2.900	3.100	0.114	0.122
E1	1.500	1.800	0.059	0.071
k	0.200 MIN		0.008 MIN	
b	0.180	0.300	0.007	0.012
e	0.500 TYP		0.020 TYP	
L	0.300	0.500	0.012	0.020

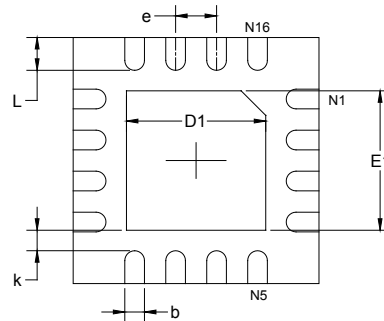
## PACKAGE INFORMATION

### PACKAGE OUTLINE DIMENSIONS

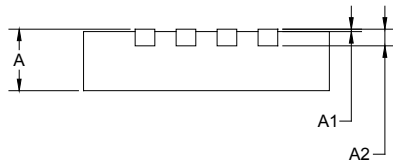
#### TQFN-3×3-16L



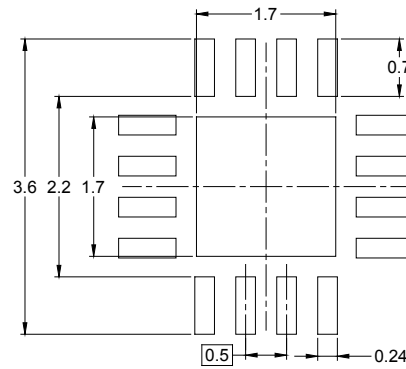
TOP VIEW



BOTTOM VIEW



SIDE VIEW



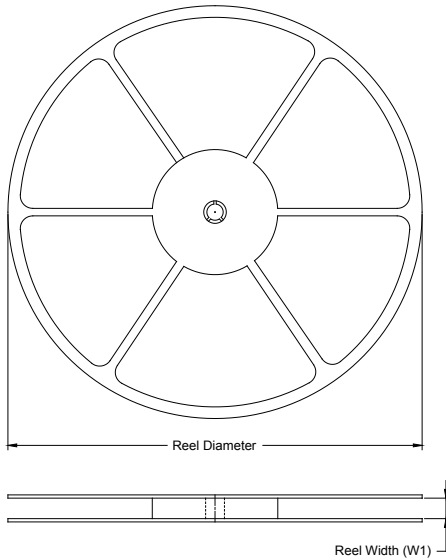
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203 REF		0.008 REF	
D	2.900	3.100	0.114	0.122
D1	1.600	1.800	0.063	0.071
E	2.900	3.100	0.114	0.122
E1	1.600	1.800	0.063	0.071
k	0.200 MIN		0.008 MIN	
b	0.180	0.300	0.007	0.012
e	0.500 TYP		0.020 TYP	
L	0.300	0.500	0.012	0.020

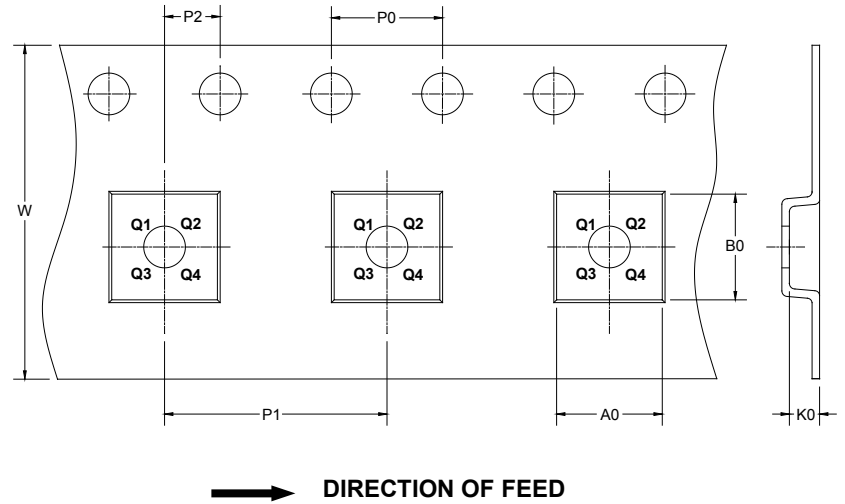
# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TQFN-3×3-16L	13"	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1
TDFN-3×3-10L	13"	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1

DD0001



## PACKAGE INFORMATION

### CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

DD0002